

In claim 70, line 6 change "compressible" to read --
compliant --.

Amend claims 71 and 72 as follows:

¹⁹71. (Amended) A semiconductor chip assembly comprising:

- (a) a semiconductor chip having contacts;
(b) a support structure juxtaposed with the chip;

[structure;]

(c) a plurality of terminals overlying said support structure;

[(c)] (d) a layer of a [compressible] compliant material disposed between said terminals and said support structure and supporting [at least some of] said terminals above said support structure; and

[(d)] (e) flexible leads interconnecting said terminals with said contacts of said chip so that said terminals are movable with respect to said contacts.

²⁰72. (Amended) A semiconductor chip assembly as claimed in claim [68] ¹⁷~~69~~ or claim [70] ¹⁹~~71~~ wherein said support structure includes a unitary rectangular ring surrounding the chip.

In claim 73, line 2 change "compressible" to read --
compliant --.

In claim 74, line 2 change "substate" to read --
substrate--.

Amend claim 76 as follows:

²⁴76. (Amended) A semiconductor chip assembly as claimed in claim ¹⁵~~67~~ or claim ¹⁷~~69~~ further comprising a [substate] substrate having contact pads thereon, said sheetlike element being disposed between said chip and said substrate, each said terminal being connected to one said contact pad of said substrate.

²⁵77. (Amended) A semiconductor chip assembly as claimed in claim ¹⁶~~68~~ or claim ¹⁹~~71~~ further comprising a [substate] substrate having contact pads thereon, each said terminal being connected to one said contact pad of said substrate.

Add new claims 81 and 82.